

Sensor for Heart Rate Monitor ICs

Optical Sensor for Heart Rate Monitor IC

BH1792GLC

General Description

BH1792GLC is optical sensor for heart rate monitor IC in which LED driver, green light and IR detection photodiode are incorporated. This device drives LED and provides the intensity of light reflected from body. LED brightness can be adjusted by LED driver current. The photodiode having the high sensitivity for green light and excellent wavelength selectivity achieves accurate pulse wave detection.

Key Specifications

- VCC Voltage Range: 2.5V to 3.6V
- Current Consumption: 200μA(Typ)
- Standby Mode Current: 0.8μA (Typ)
- Operating Temperature Range: -20°C to +85°C

Package

WLGA010V28

W(Typ) x D(Typ) x H(Max)

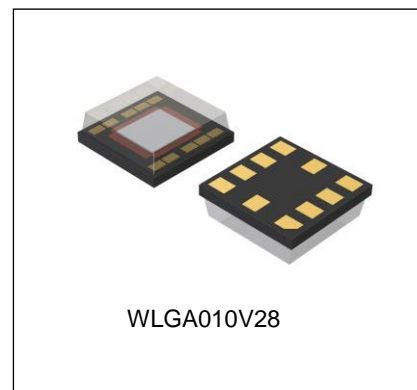
2.8mm x 2.8mm x 1.0mm

Features

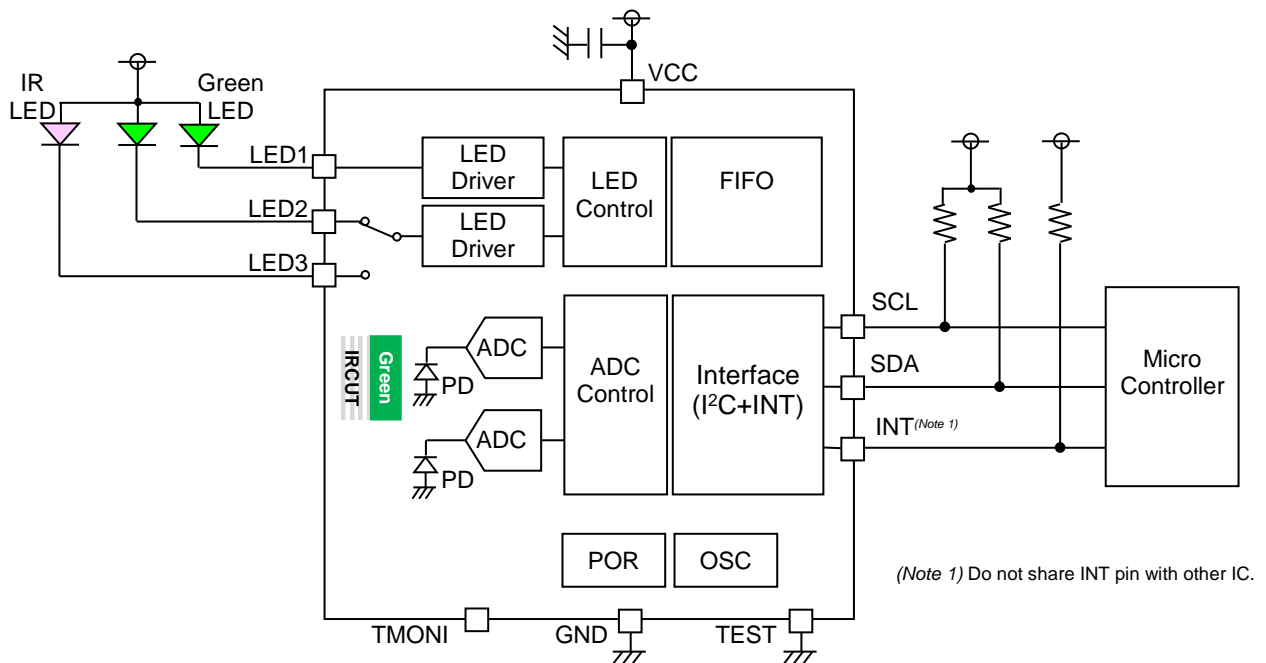
- Build-in green photodiode with excellent wavelength selective green filter and IR cut filter.
- Built-in IR photodiode for touch detection.
- Correspond to high sampling frequency. (1024Hz)
- LED driver with current selection.
- I2C bus Interface(f/s mode support)
- Built-in FIFO

Applications

- Wearable device, smart phone, Tablet PC.



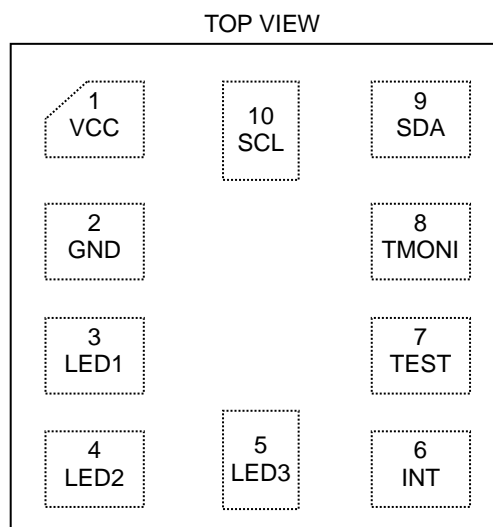
Typical Application Circuit



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Pin Configuration



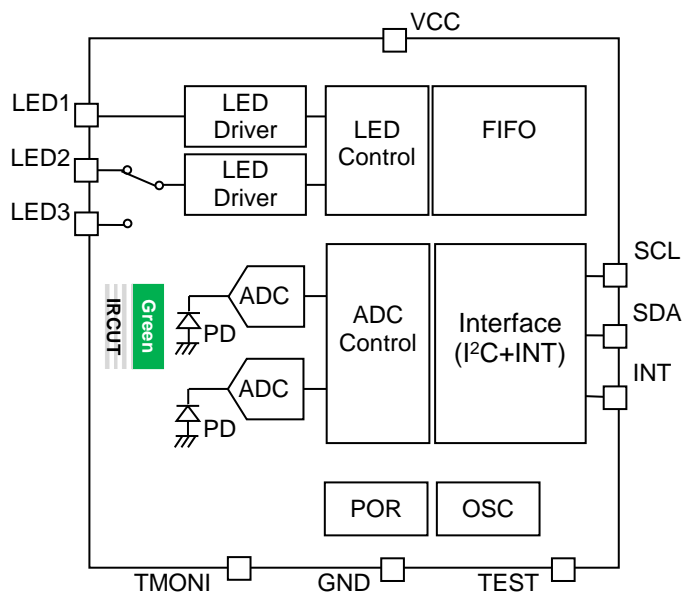
Pin Description

| Pin No. | Pin Name | Function |
|---------|----------|-----------------------------------|
| 1 | VCC | Power supply ^(Note 1) |
| 2 | GND | Ground |
| 3 | LED1 | LED1 driver output |
| 4 | LED2 | LED2 driver output |
| 5 | LED3 | LED3 driver output |
| 6 | INT | Interrupt ^(Note 2) |
| 7 | TEST | TEST pin (Connect to GND) |
| 8 | TMONI | TEST Monitor pin (open) |
| 9 | SDA | I ² C bus serial data |
| 10 | SCL | I ² C bus serial clock |

(Note 1) Dispose a bypass capacitor as close as possible to the IC

(Note 2) Do not share INT pin with other IC

Block Diagram



Description of Blocks

- IRCUT
This filter passes visible light and blocks infrared light.
- GREEN
Green color pass filter
- PD
Photodiodes (PD) convert light into current.
- LED Driver
LED driver circuit
- ADC
AD converter
- OSC
Internal oscillator generates clock for internal logic.
- POR
Power on reset
- Interface (I²C+INT)
I²C bus and interrupt pin Interface block
- ADC control
AD converter control block
- LED control
LED driver control block
- FIFO
FIFO circuit

Absolute Maximum Ratings (Ta=25°C)

| Parameter | Symbol | Rating | Unit |
|---|---------------------|--------------|------|
| Supply Voltage | V _{CC_MR} | 4.5 | V |
| Terminal input Voltage1 ^(Note 1) | V _{IN_MR} | -0.3 to +4.5 | V |
| Terminal input Voltage2 ^(Note 2) | V _{LED_MR} | 7 | V |
| Storage Temperature Range | T _{stg} | -40 to +100 | °C |
| Maximum Junction Temperature | T _{jmax} | 100 | °C |

(Note 1) INT, SCL, SDA pins

(Note 2) LED1, LED2, LED3 pins

Caution1: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Caution2: Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB boards with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.

Thermal Resistance^(Note1)

| Parameter | Symbol | Thermal Resistance (Typ) | | Unit |
|---|---------------|--------------------------|--------------------------|------|
| | | 1s ^(Note 3) | 2s2p ^(Note 4) | |
| WLGA010V28 | | | | |
| Junction to Ambient | θ_{JA} | 319.5 | 182.1 | °C/W |
| Junction – Top Characterization Parameter ^(Note 2) | Ψ_{JT} | 102 | 65 | °C/W |

(Note 1) Based on JESD51-2A(Still-Air).

(Note 2) The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.

(Note 3) Using a PCB board based on JESD51-3.

| Layer Number of Measurement Board | Material | Board Size |
|-----------------------------------|----------|----------------------------|
| Single | FR-4 | 114.3mm x 76.2mm x 1.57mmt |

| Top | |
|-----------------------|-----------|
| Copper Pattern | Thickness |
| Footprints and Traces | 70μm |

(Note 4) Using a PCB board based on JESD51-7.

| Layer Number of Measurement Board | Material | Board Size |
|-----------------------------------|----------|---------------------------|
| 4 Layers | FR-4 | 114.3mm x 76.2mm x 1.6mmt |

| Top | | 2 and 3 Internal Layers | | Bottom | |
|-----------------------|-----------|-------------------------|-----------|-----------------|-----------|
| Copper Pattern | Thickness | Copper Pattern | Thickness | Copper Pattern | Thickness |
| Footprints and Traces | 70μm | 74.2mm x 74.2mm | 35μm | 74.2mm x 74.2mm | 70μm |

Recommended Operating Conditions

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|------------------|-----|-----|-----|------|
| Operating Temperature | Topr | -20 | +25 | +85 | °C |
| Supply Voltage | V _{CC} | 2.5 | 3.0 | 3.6 | V |
| Terminal Input Voltage <i>(Note 1)</i> | V _{LED} | 0.7 | - | 5.5 | V |

(Note 1) LED1, LED2, LED3 pins

Electrical Characteristics

(Unless otherwise specified V_{CC}=3.0V, T_a=25°C, MSR=000)

| Parameter | Symbol | Min | Typ | Max | Unit | Conditions |
|---|--------------------|------|------|------|-------|--|
| Supply Current | I _{CC1} | - | 200 | 400 | μA | No LED emitting |
| Supply Current during LED current drive | I _{CC2} | - | 1.4 | 3.0 | mA | LED emitting |
| Standby Mode Current | I _{CC3} | - | 0.8 | 1.5 | μA | No input light |
| Green Data Count Value | D _{GREEN} | 3000 | 5100 | 7200 | count | EV=10uW/cm ² <i>(Note 1)</i> |
| IR Data Count Value | D _{IR} | 2500 | 4300 | 6000 | count | EV=200uW/cm ² <i>(Note 2)</i> |
| Dark Count Value (Green Data) | S _{GR_0} | - | - | 200 | count | No input light |
| Dark Count Value (IR Data) | S _{IR_0} | - | - | 200 | count | No input light |
| Synchronized Signal Interval | T _{sync} | - | 1 | - | s | |
| LED Emitting Time | t _{wLED} | - | 300 | 400 | μs | |
| LED Output Current | I _{LED} | 1 | 2 | 3 | mA | LED pin input voltage = 1.0V LED_CURRENT=2mA Mode |
| LED Off Leakage Current | I _{OFF} | - | 0 | 1 | μA | LED terminal voltage = 5.0V |
| OSC Cycle | t _{OSC} | - | 0.5 | 0.67 | μs | |
| L Input Voltage <i>(Note 3)</i> | V _{IL} | - | - | 0.54 | V | |
| H Input Voltage <i>(Note 3)</i> | V _{IH} | 1.26 | - | - | V | |
| L Input Current <i>(Note 3)</i> | V _{IL} | -10 | - | - | μA | V _{IL} =GND |
| H Input Current <i>(Note 3)</i> | V _{IH} | - | - | 10 | μA | V _{IH} =V _{CC} |
| L Output Voltage <i>(Note 4)</i> | V _{OL} | 0 | - | 0.4 | V | I _L =3mA |

(Note 1) Green LED is used as optical source.

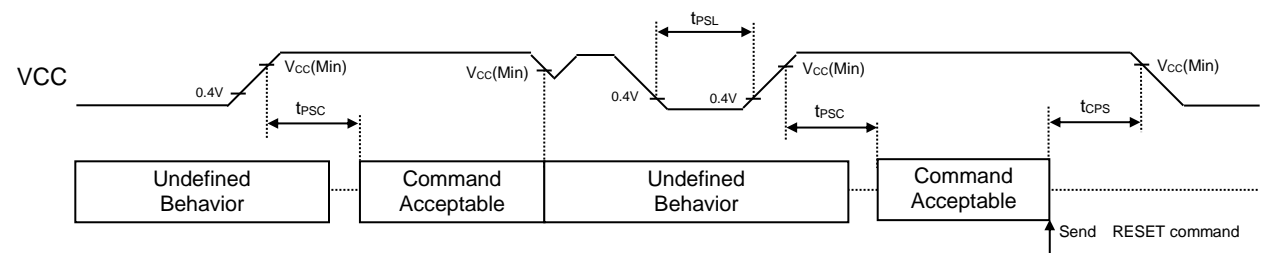
(Note 2) IR LED is used as optical source.

(Note 3) SDA, SCL pins

(Note 4) SDA, INT pins

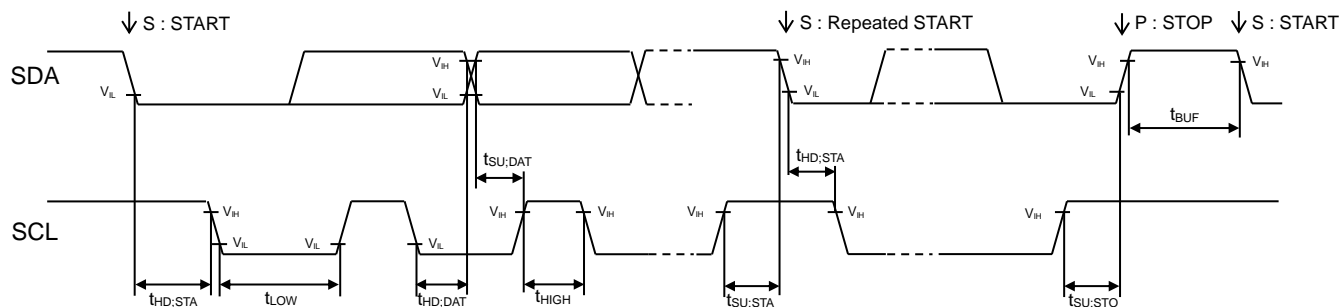
Power Sequence (Unless otherwise specified VCC=3.0V, Ta=25°C)

There is a Power on reset function which monitors VCC power.
All registers are reset by Power ON Reset function when power is supplied to VCC.



| Parameter | Symbol | Min | Typ | Max | Unit | Conditions |
|-----------------------------------|--------|-----|-----|-----|------|------------|
| Command input time after power-on | tPSC | 2 | - | - | ms | |
| Power supply OFF time | tPSL | 1 | - | - | ms | |
| Wait time from power down command | tCPS | 100 | - | - | μs | |

tPSC after VCC power-on, command can be input.
Internal condition becomes undefined when VCC is lower than recommended operating voltage range. In this case power off VCC once and power-on again.
Please keep VCC Low (VCC<0.4V) more than tPSL before VCC power-on.
Send RESET command before tCPS from power-off VCC.

I²C Bus Timing Characteristics (Unless otherwise specified VCC=3.0V, Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Units | Conditions |
|--------------------------------------|---------------------|------|------|------|-------|------------|
| SCL Clock frequency | f _{SCL} | 0 | - | 400 | kHz | |
| 'L' Period of the SCL Clock | t _{LOW} | 1.3 | - | - | μs | |
| 'H' Period of the SCL Clock | t _{HIGH} | 0.6 | - | - | μs | |
| Setup Time for Repeated START | t _{SU;STA} | 0.6 | - | - | μs | |
| Hold Time for START | t _{HD;STA} | 0.6 | - | - | μs | |
| Data Setup Time | t _{SU;DAT} | 100 | - | - | ns | |
| Data Hold Time | t _{HD;DAT} | 0 | - | - | μs | |
| Setup Time for STOP | t _{SU;STO} | 0.6 | - | - | μs | |
| Bus Free Time between STOP and START | t _{BUF} | 1.3 | - | - | μs | |

I²C bus Communication

1. Write format

(1) Indicate register address

| | | | | | | |
|---|---------------|--------|-----|------------------|-----|---|
| S | Slave Address | W 0 | ACK | Register Address | ACK | P |
|---|---------------|--------|-----|------------------|-----|---|

(2) Write data after indicating register address

| | | | | | |
|---|---------------|--------|-----|------------------|-----|
| S | Slave Address | W 0 | ACK | Register Address | ACK |
|---|---------------|--------|-----|------------------|-----|

| | | | | | | |
|--|-----|-----|-----|--|-----|---|
| Data specified at register address field | ACK | ... | ACK | Data specified at register address field + N | ACK | P |
|--|-----|-----|-----|--|-----|---|

2. Read format

(1) Read data after indicating register address (Master issues restart condition)

| | | | | | |
|---|---------------|--------|-----|------------------|-----|
| S | Slave Address | W 0 | ACK | Register Address | ACK |
|---|---------------|--------|-----|------------------|-----|

| | | | | | |
|---|---------------|--------|-----|--|-----|
| S | Slave Address | R 1 | ACK | Data specified at register address field | ACK |
|---|---------------|--------|-----|--|-----|

| | | | | | | |
|--|-----|-----|-----|--|------|---|
| Data specified at register address field + 1 | ACK | ... | ACK | Data specified at register address field + N | NACK | P |
|--|-----|-----|-----|--|------|---|

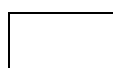
(2) Read data from the specified register

| | | | | | |
|---|---------------|--------|-----|--|-----|
| S | Slave Address | R 1 | ACK | Data specified at register address field | ACK |
|---|---------------|--------|-----|--|-----|

| | | | | | | |
|--|-----|-----|-----|--|------|---|
| Data specified at register address field + 1 | ACK | ... | ACK | Data specified at register address field + N | NACK | P |
|--|-----|-----|-----|--|------|---|



from master to slave



from slave to master

Typical Performance Curves

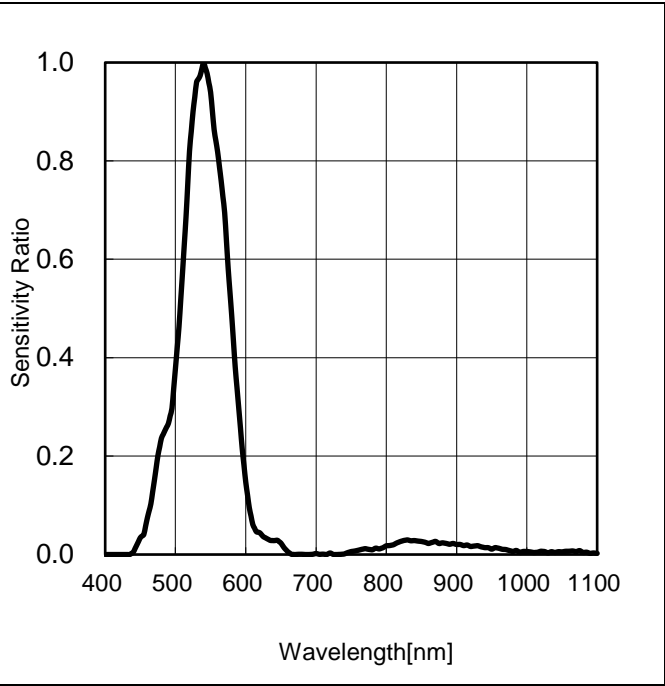


Figure 1. Sensitivity Ratio vs Wavelength
("Green Spectral Response")

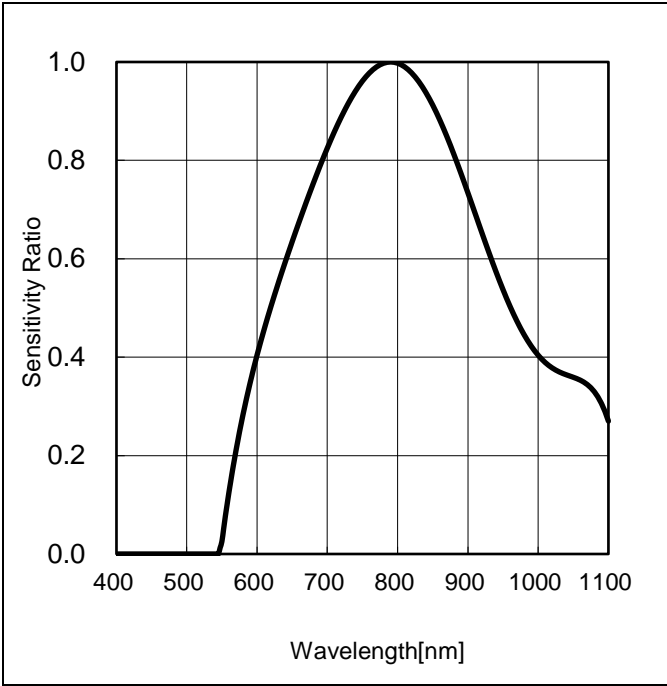


Figure 2. Sensitivity Ratio vs Wavelength
("IR Spectral Response")

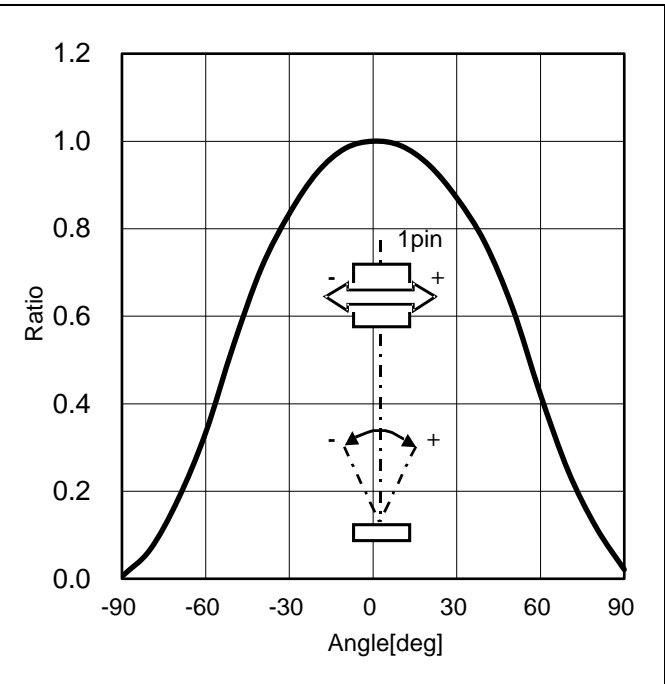


Figure 3. Green Ratio vs Angle
("Directional Characteristics 1")

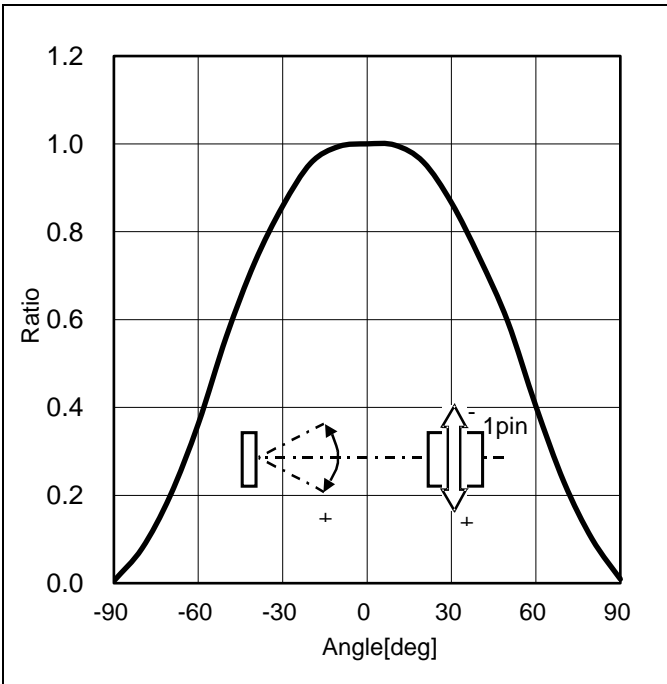


Figure 4. Green Ratio vs Angle
("Directional Characteristics 2")

Typical Performance Curves

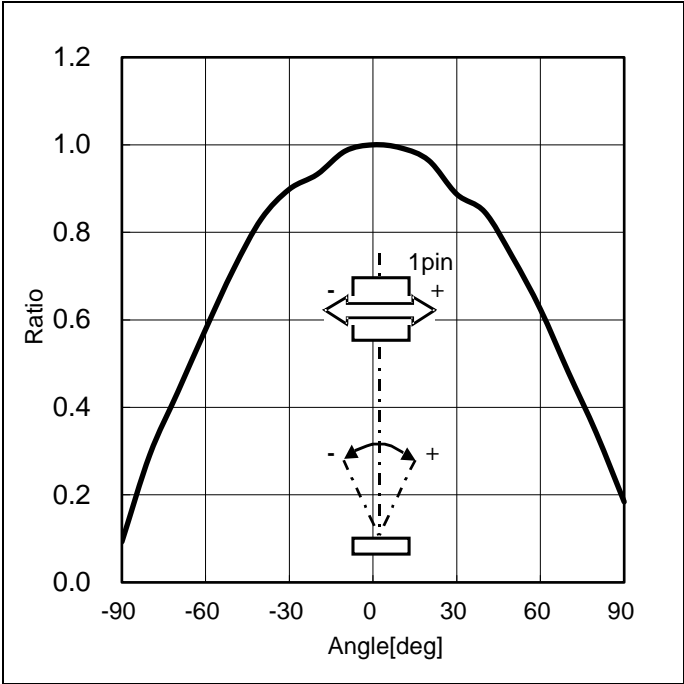


Figure 5. IR Ratio vs Angle
("Directional Characteristics 1")

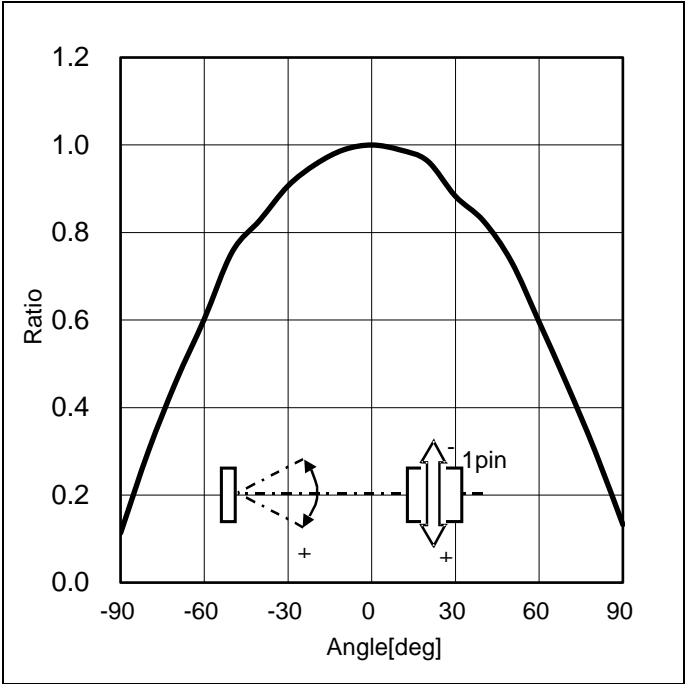


Figure 6. IR Ratio vs Angle
("Directional Characteristics 2")

I²C bus Slave address

Slave address is "1011011".

Register Map (Note 1)

Register Map

| Register Address | Register Name | R/W | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------------------|-----------------|-----|-----------------------|----|-------------------|---------|----|----------|--------------|-----------|
| 0x0F | MANUFACTURER_ID | R | MANUFACTURER_ID [7:0] | | | | | | | |
| 0x10 | PART_ID | R | PART_ID[7:0] | | | | | | | |
| 0x40 | RESET | RW | SW RESET | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| 0x41 | MEAS_CONTROL1 | RW | RDY | 0 | 0 | SEL_ADC | 0 | MSR[2:0] | | |
| 0x42 | MEAS_CONTROL2 | RW | LED_EN1[1:0] | | LED_CURRENT1[5:0] | | | | | |
| 0x43 | MEAS_CONTROL3 | RW | LED_EN2 | 0 | LED_CURRENT2[5:0] | | | | | |
| 0x44 | MEAS_CONTROL4 | RW | TH_IR[7:0] | | | | | | | |
| 0x45 | | RW | TH_IR[15:8] | | | | | | | |
| 0x46 | MEAS_CONTROL5 | RW | 0 | 0 | 0 | 0 | 0 | 0 | INT_SEL[1:0] | |
| 0x47 | MEAS_START | RW | 0 | 0 | 0 | 0 | 0 | 0 | 0 | MEAS_ST |
| 0x48 | MEAS_SYNC | RW | 0 | 0 | 0 | 0 | 0 | 0 | 0 | MEAS_SYNC |
| 0x4B | FIFO_LEV | R | 0 | 0 | FIFO_LEV[5:0] | | | | | |
| 0x4C | FIFODATA0 | R | FIFODATA0 [7:0] | | | | | | | |
| 0x4D | | R | FIFODATA0 [15:8] | | | | | | | |
| 0x4E | FIFODATA1 | R | FIFODATA1 [7:0] | | | | | | | |
| 0x4F | | R | FIFODATA1 [15:8] | | | | | | | |
| 0x50 | IRDATA_LEDOFF | R | IRDATA_LEDOFF [7:0] | | | | | | | |
| 0x51 | | R | IRDATA_LEDOFF [15:8] | | | | | | | |
| 0x52 | IRDATA_LEDON | R | IRDATA_LEDON [7:0] | | | | | | | |
| 0x53 | | R | IRDATA_LEDON [15:8] | | | | | | | |
| 0x54 | GDATA_LEDOFF | R | GDATA_LEDOFF [7:0] | | | | | | | |
| 0x55 | | R | GDATA_LEDOFF [15:8] | | | | | | | |
| 0x56 | GDATA_LEDON | R | GDATA_LEDON [7:0] | | | | | | | |
| 0x57 | | R | GDATA_LEDON [15:8] | | | | | | | |
| 0x58 | INT_CLEAR | R | - | - | - | - | - | - | - | - |

(Note 1) Do not write any commands to other addresses except above. Do not write '1' to the fields in which value is '0' in above table.

(0x0F) MANUFACTURER_ID

| Fields | Function |
|----------------------|------------------------|
| MANUFACTURER_ID[7:0] | Manufacturer ID : 0xE0 |

(0x10) PART_ID

| Fields | Function |
|--------------|----------------|
| PART_ID[7:0] | Part ID : 0x0E |

(0x40) RESET

| Fields | Function |
|---------|---|
| SWRESET | Reset all registers when writing "1". "1" is not written in register. Read value is always "0". |

default value 0x00

(0x41) MEAS_CONTROL1

| Fields | Function |
|----------|---|
| RDY | 0 : Prohibited 1 : OSC block is active |
| SEL_ADC | Select channel of ADC measurement 0 : GREEN Measurement Mode LED1 and LED2 drivers are active. 1 : IR Measurement Mode Only in Non Synchronized Measurement Mode and Single Measurement Mode this mode can be used. LED3 driver is active. |
| MSR[2:0] | Select Measurement Mode |

default value 0x00

< MSR >

Select measurement mode.

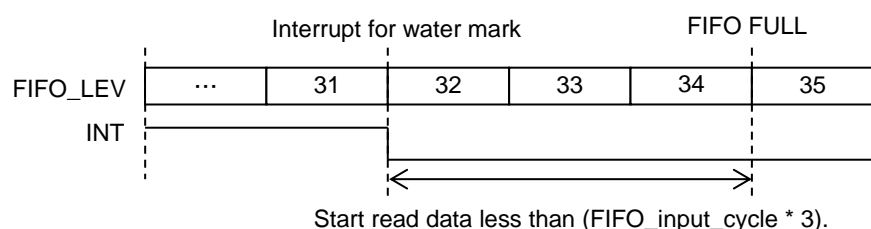
| MSR | Measurement mode | LED Emitting Frequency | Output Data Rate | FIFO storing | FIFO_input_cycle[ms] | Measurement time after receiving MEAS_SYNC |
|-----|-----------------------------------|------------------------|------------------|--------------|----------------------|--|
| 000 | 32Hz Mode | 128Hz setting | 32Hz setting | Storing | $T_{sync}/32$ | 32 |
| 001 | 128Hz Mode | 128Hz setting | 128Hz setting | Storing | $T_{sync}/128$ | 128 |
| 010 | 64Hz Mode | 256Hz setting | 64Hz setting | Storing | $T_{sync}/64$ | 64 |
| 011 | 256Hz Mode | 256Hz setting | 256Hz setting | Storing | $T_{sync}/256$ | 256 |
| 100 | Prohibited | - | - | - | - | - |
| 101 | 1024Hz Mode | 1024Hz setting | 1024Hz setting | Storing | $T_{sync}/1024$ | 1024 |
| 110 | Non Synchronized Measurement Mode | 4Hz setting | 4Hz setting | No storing | - | - |
| 111 | Single Measurement Mode | - | - | No storing | - | - |

Synchronized Measurement Mode (MSR : 000 to 101)

Adjust LED emitting frequency and output data rate by synchronizing with MEAS_SYNC received interval. After receiving MEAS_SYNC, the measurements for a set number of times are performed. After finishing measurements for a set number of times, measurement stops until receiving MEAS_SYNC. When starting measurement, LED emission is operated with default frequency. And start synchronized operation after receiving next MEAS_SYNC. Use the measurement value of after starting synchronized operation

LED_CURRENT1 and LED_CURRENT2 can be changed during measurement. The value becomes effective when receiving MEAS_SYNC. Send SWRESET first, in case of changing other registers above.

Measurement data is stored in FIFO. FIFO can store 35 samples. Refer to FIFODATA0 and FIFODATA1 for data to store in FIFO. It becomes FULL condition when the number of samples reaches 35, and stop storing samples in FIFO. Water Mark Interrupt occurs when the number of samples reaches 32 or more. Refer INT_SEL for setting interrupt output of INT pin. After the interruption, read FIFO data before it becomes FULL condition.



Non Synchronized Measurement Mode

Measurement starts after receiving MEAS_ST. LED_CURRENT1 and LED_CURRENT2 can be changed during measurement. New value becomes effective when receiving MEAS_ST. Send SWRESET first, in case of changing other registers above.

LED emitting frequency depends on OSC oscillation frequency.

LED emitting frequency: $(499968 * t_{osc})$ s

Single Measurement mode

Measurement starts after receiving MEAS_ST. Send SWRESET first, in case of changing registers. After finishing measurement, the measurement stops until receiving MEAS_ST.

(0x42) MEAS_CONTROL2

| Fields | Function |
|-------------------|-------------------------------|
| LED_EN1[1:0] | Select the mode of LED driver |
| LED_CURRENT1[5:0] | Set the current of LED driver |

default value 0x00

(0x43) MEAS_CONTROL3

| Fields | Function |
|-------------------|-------------------------------|
| LED_EN2 | Select the mode of LED driver |
| LED_CURRENT2[5:0] | Set the current of LED driver |

default value 0x00

<LED_EN1/LED_EN2>

Select the mode of LED driver

| LED_EN1[1:0] | LED_EN2 | LED1 | LED2 | LED3 | |
|--------------|---------|--------------------------|--------------------------|--------------------------|----------|
| 00 | x | Pulsed Light Emission | Pulsed Light Emission | Pulsed Light Emission | (Note 1) |
| 01 | x | ON | OFF | OFF | (Note 2) |
| 10 | 0 | OFF | ON | OFF | (Note 2) |
| 10 | 1 | OFF | OFF | ON | (Note 2) |
| 11 | 0 | ON | ON | OFF | (Note 2) |
| 11 | 1 | ON | OFF | ON | (Note 2) |

(Note 1) LED driver is selected by SEL_ADC. Use for measurement.

(Note 2) This setting is for the operation check of LED.

<LED_CURRENT1>

Adjust the output current of
LED1 and LED2 drivers.
New parameters becomes effective
when receiving MEAS_ST.

| LED_CURRENT1[5:0] | Current setting mode |
|-------------------|----------------------|
| 0x00 | Stop emission mode |
| 0x01 | 1mA mode |
| 0x02 | 2mA mode |
| 0x03 | 3mA mode |
| ... | ... |
| 0x09 | 9mA mode |
| 0x0A | 10mA mode |
| 0x0B | 11mA mode |
| ... | ... |
| 0x3D | 61mA mode |
| 0x3E | 62mA mode |
| 0x3F | 63mA mode |

<LED_CURRENT2>

Adjust the output current of LED3 driver.
New parameters becomes effective
when receiving MEAS_ST.

| LED_CURRENT2[5:0] | Current setting mode |
|-------------------|----------------------|
| 0x00 | Stop emission mode |
| 0x01 | 1mA mode |
| 0x02 | 2mA mode |
| 0x03 | 3mA mode |
| ... | ... |
| 0x09 | 9mA mode |
| 0x0A | 10mA mode |
| 0x0B | 11mA mode |
| ... | ... |
| 0x3D | 61mA mode |
| 0x3E | 62mA mode |
| 0x3F | 63mA mode |

(0x44/0x45) MEAS_CONTROL4

| Fields | Function |
|-------------|------------------------------|
| TH_IR[15:0] | IR Interrupt Threshold Value |

default value 0xFFFFC

(0x46) MEAS_CONTROL5

| Fields | Function |
|--------------|---|
| INT_SEL[1:0] | <p>Select interrupt factor of INT pin INT pin outputs L when the interruption factor occurs.</p> <p>00 : Disenable (No interrupt output)</p> <p>01 : Water Mark interrupt of FIFO Interrupt when the stored sample number reaches 32 or more, and it's cleared when the number of sample falls below 32.</p> <p>10 : IR threshold judgement interruption Use only in Non Synchronized Measurement Mode. Compare IRDATA_LEDON[15:4] and TH_IR[15:4] when updating data. Interruption occurs when IRDATA_LEDON[15:4] is TH_IR[15:4] or more. Interruption will be cleared when reading INT_CLEAR.</p> <p>11 : Measurement completion interruption In Single Measurement Mode this is effective. Interrupt when the measurement finished. Interruption will be cleared when reading INT_CLEAR.</p> |

default value 0x00

(0x47) MEAS_START

| Fields | Function |
|---------|---|
| MEAS_ST | <p>Flag of start measurement</p> <p>0 : Prohibited</p> <p>1 : Measurement start Starts measurement by writing "MEAS_ST=1" after setting up "RDY =1" (Non Synchronized Measurement Mode, Single Measurement Mode). When stop measurement, write "SWRESET=1" without writing "MEAS_ST=0". Restart measurement restart by writing "MEAS_ST=1", while it is in Single Measurement Mode.</p> |

default value 0x00

(0x48) MEAS_SYNC

| Fields | Function |
|-----------|---|
| MEAS_SYNC | <p>Input measurement synchronization signal</p> <p>0 : Prohibited</p> <p>1 : Input synchronization signal Starts measurement by writing "MEAS_SYNC=1" after setting up "MEAS_ST =1" (Synchronized Measurement Mode). Send MEAS_SYNC in every 1 second. Measurements set in "MSR" are performed within the interval of sending MEAS_SYNC. '1' can't be written in this register. Always '0' is read.</p> |

default value 0x00

(0x4B) FIFO_LEV

| Fields | Function |
|---------------|--|
| FIFO_LEV[5:0] | Number of stored sample in FIFO FIFO_LEV=0x00 : FIFO Empty FIFO_LEV=0x23 : FIFO FULL |

default value 0x00

(0x4C/0x4D) FIFODATA0

| Fields | Function |
|-----------------|--------------------|
| FIFODATA0[15:0] | FIFO Output Data 0 |

default value 0x0000

(0x4E/0x4F) FIFODATA1

| Fields | Function |
|-----------------|--------------------|
| FIFODATA1[15:0] | FIFO Output Data 1 |

default value 0x0000

Built-in 35 slot of FIFO.

FIFO store 4 byte data by 1 slot.

Measurement data stored in FIFO is determined by Measurement Mode.

Measurement data is stored in FIFO in every measurement.

Stop storing data in FIFO, after FIFO become FULL condition.

| Measurement Mode | FIFODATA0 | FIFODATA1 |
|-----------------------------------|---------------|--------------|
| 32Hz Mode | GDATA_LED OFF | GDATA_LED ON |
| 128Hz Mode | GDATA_LED OFF | GDATA_LED ON |
| 64Hz Mode | GDATA_LED OFF | GDATA_LED ON |
| 256Hz Mode | GDATA_LED OFF | GDATA_LED ON |
| 1024Hz Mode | No storing | GDATA_LED ON |
| Non Synchronized Measurement Mode | No storing | No storing |
| Single Measurement Mode | No storing | No storing |

(0x50/0x51) IRDATA_LED OFF

| Fields | Function |
|----------------------|---|
| IRDATA_LED OFF[15:0] | IR Data Count Value during no LED emission. |

default value 0x0000

(0x52/0x53) IRDATA_LED ON

| Fields | Function |
|---------------------|--|
| IRDATA_LED ON[15:0] | IR Data Count Value during LED emission – IR Data Count Value during no LED emission |

default value 0x0000

(0x54/0x55) GDATA_LED OFF

| Fields | Function |
|---------------------|---|
| GDATA_LED OFF[15:0] | Green Data Count Value during no LED emission |

default value 0x0000

(0x56/0x57) GDATA_LED ON

| Fields | Function |
|--------------------|--|
| GDATA_LED ON[15:0] | Green Data Count Value during LED emission |

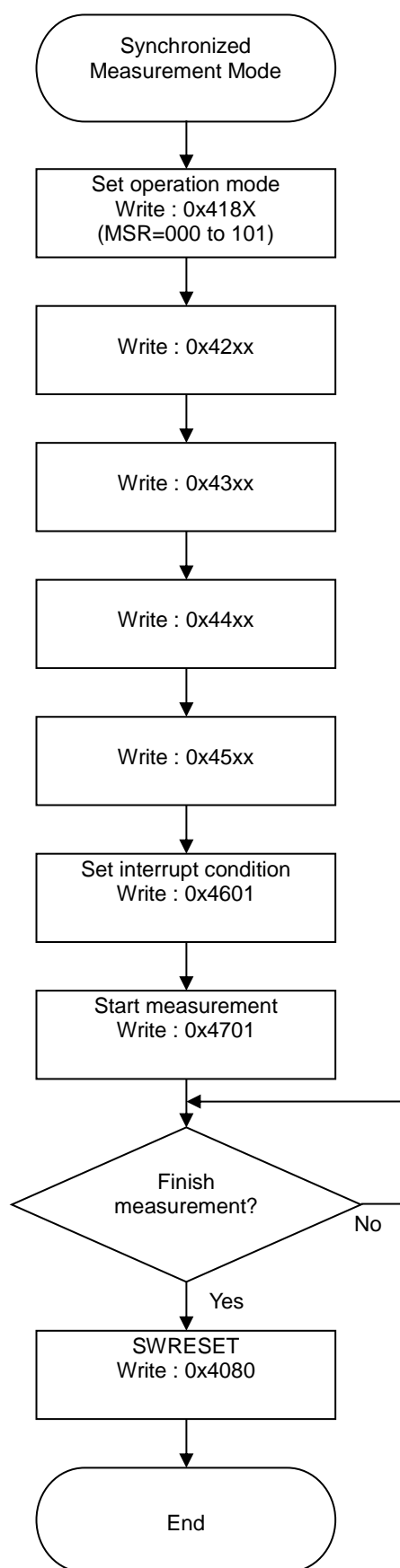
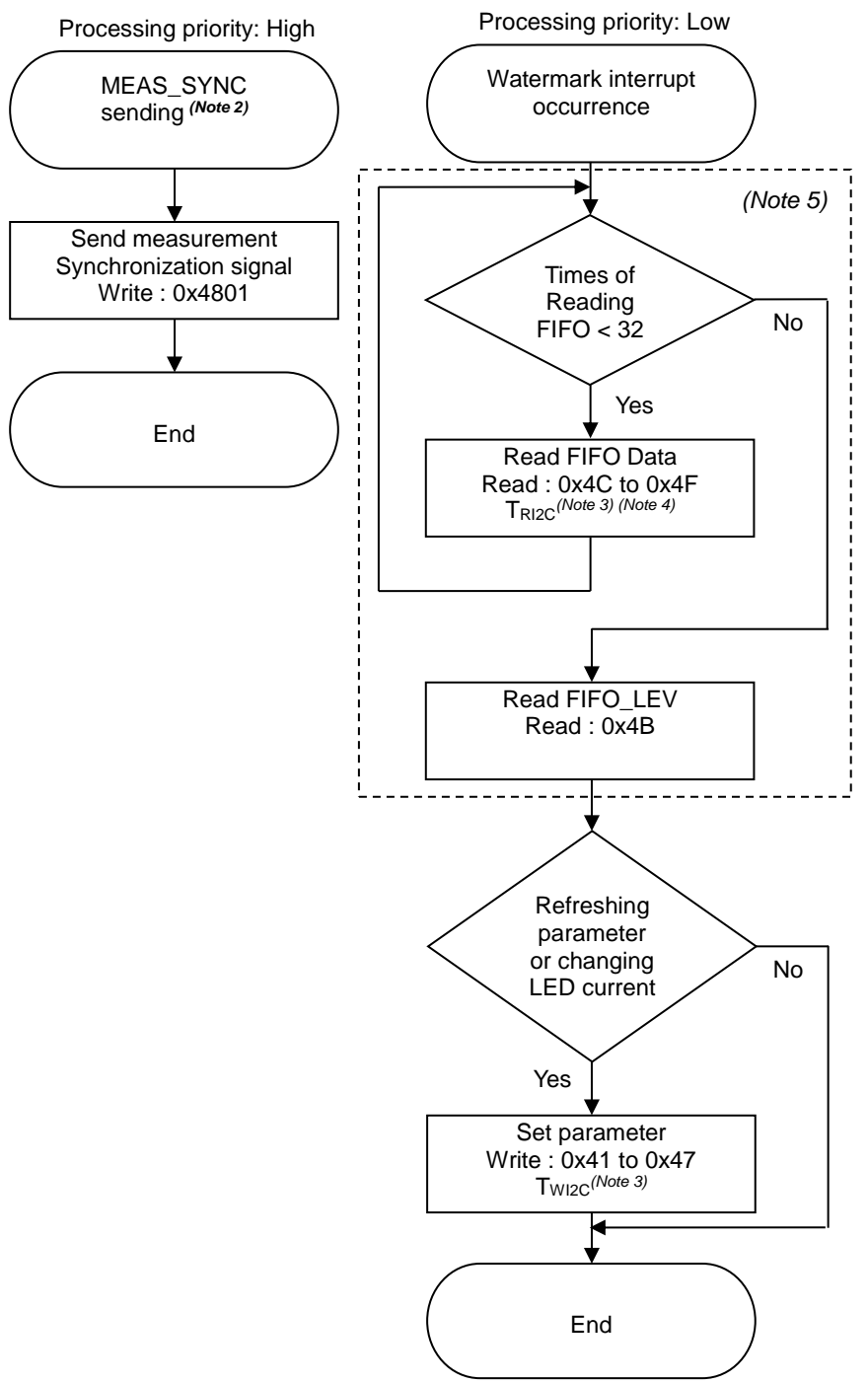
default value 0x0000

(0x58) INT_CLEAR

By reading INT_CLEAR, interruption of IR threshold judgement and measurement completion is cleared.

Control Sequence

<Synchronized Measurement Mode>

During measurement^(Note 1)^(Note 1) Between 'Start measurement' and 'Finish measurement'.^(Note 2) Send signal every 1 second.^(Note 3) T_{R12C} : time to read FIFO data. T_{W12C} : time to set parameter.^(Note 4) Data registers (0x4C, 0x4D, 0x4E, 0x4F) should be read by burst read.^(Note 5) During a period from a start of FIFO reading (write to address 0x4C) to FIFO_LEV reading (write to address 0x4B), do not communicate with this device except for FIFO reading or SYNC signal (address 0x48). When communicating with this device during FIFO reading, read FIFO_LEV and finish FIFO read sequence before other communication. If don't read FIFO_LEV before other communication, there is a possibility to lose FIFO data.

• MEAS_SYNC sending

LED emitting frequency and output data rate depend on the interval of MEAS_SYNC.

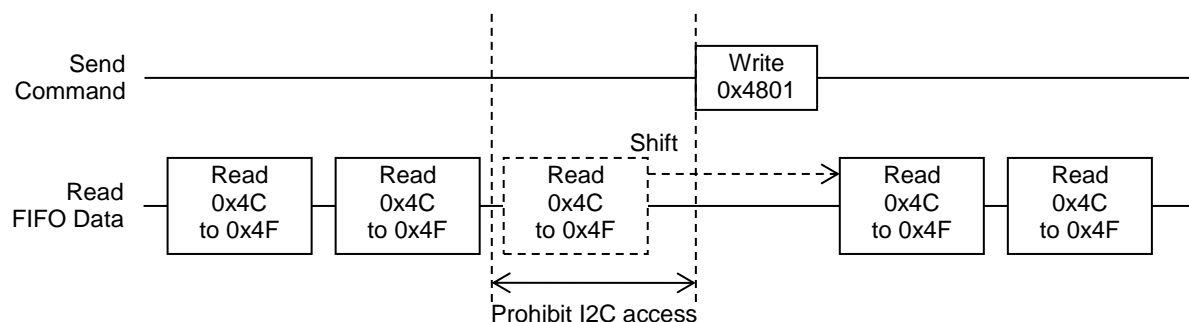
Set the priority of 'MEAS_SYNC sending' higher than 'Watermark interrupt occurrence' to send MEAS_SYNC without delay. Since processing of 'MEAS_SYNC sending' and 'Watermark interrupt occurrence' is asynchronous, avoid conflicts of I2C Bus as below.

[Avoidance example]

Prohibit I2C access for a certain period of time just before 'MEAS_SYNC sending'.

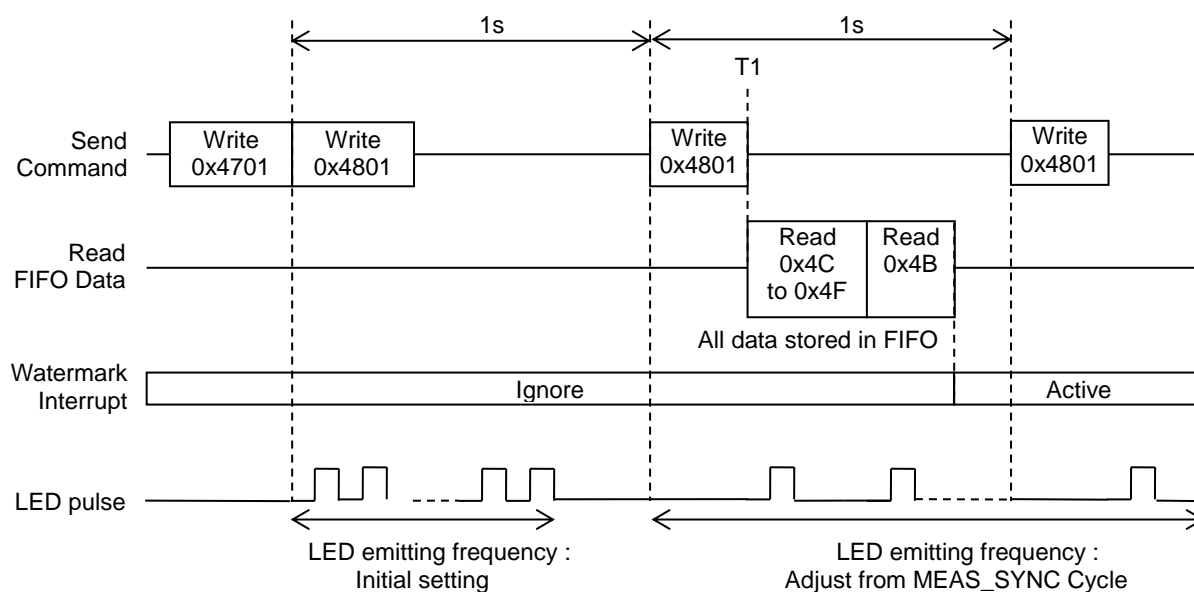
Set the prohibit time longer than 'T_{RI2C}' and 'T_{WI2C}'.

And restart reading FIFO data before it becomes FULL condition.



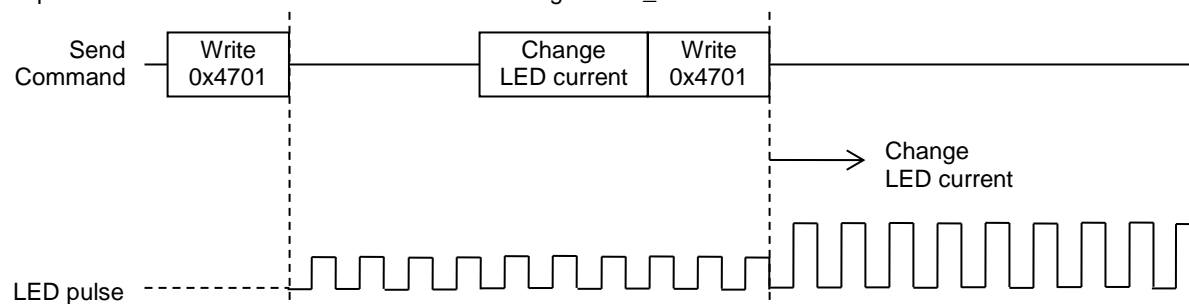
• Watermark interrupt

Since LED emitting frequency is initial setting until the device receives MEAS_SYNC twice, ignore watermark interrupt occurrence during initial setting and clear FIFO data just after sending 2nd MEAS_SYNC by reading all stored data immediately. After clearing FIFO data, treat watermark interrupt normally. At the timing of T₁ after sending 2nd MEAS_SYNC 32 data are stored in FIFO. Pulse measurement starts just after MEAS_SYNC, and FIFO data should be read before FIFO reaches full. Regarding a period that FIFO becomes full, please refer to measurement mode of MSR register.

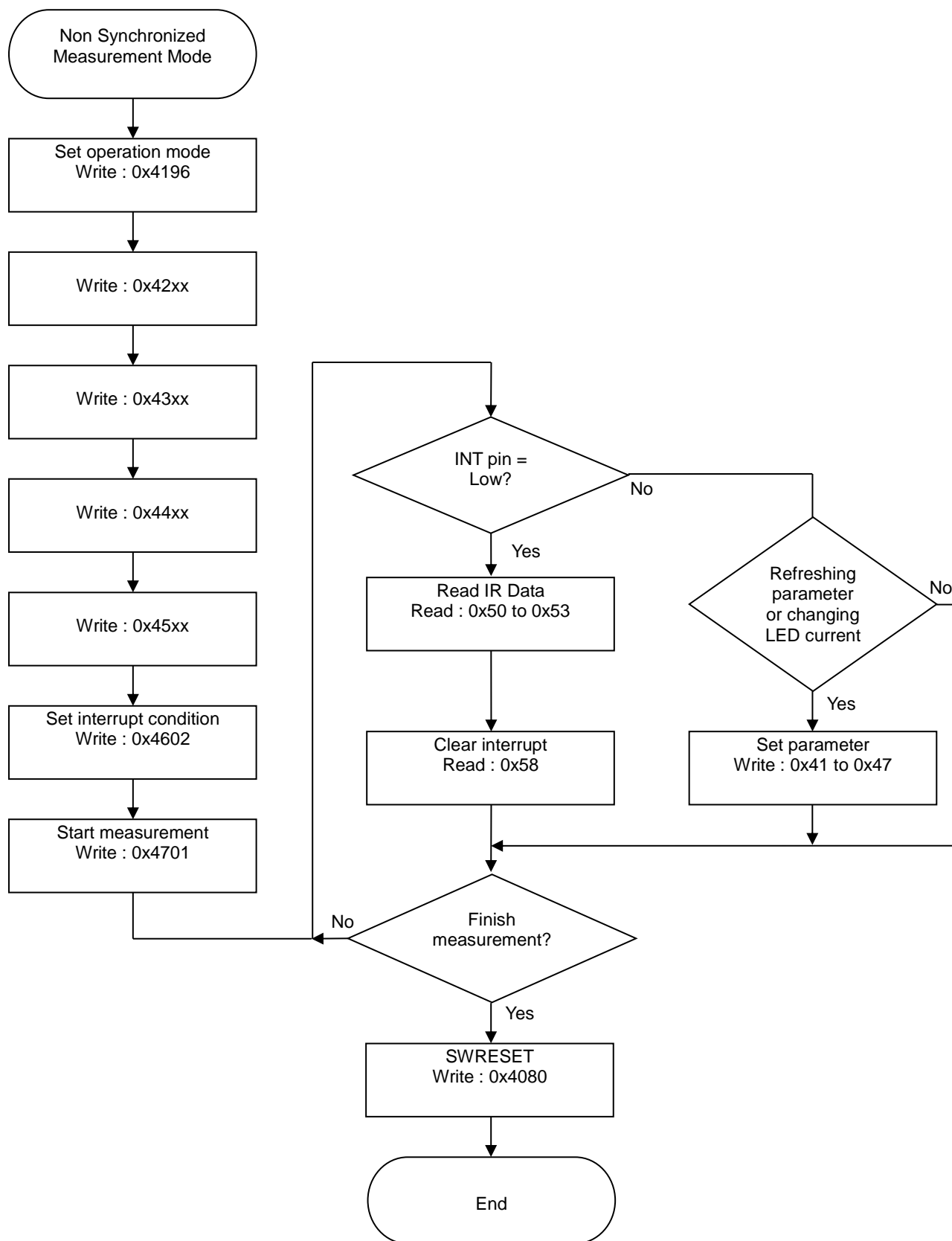


• Changing LED current

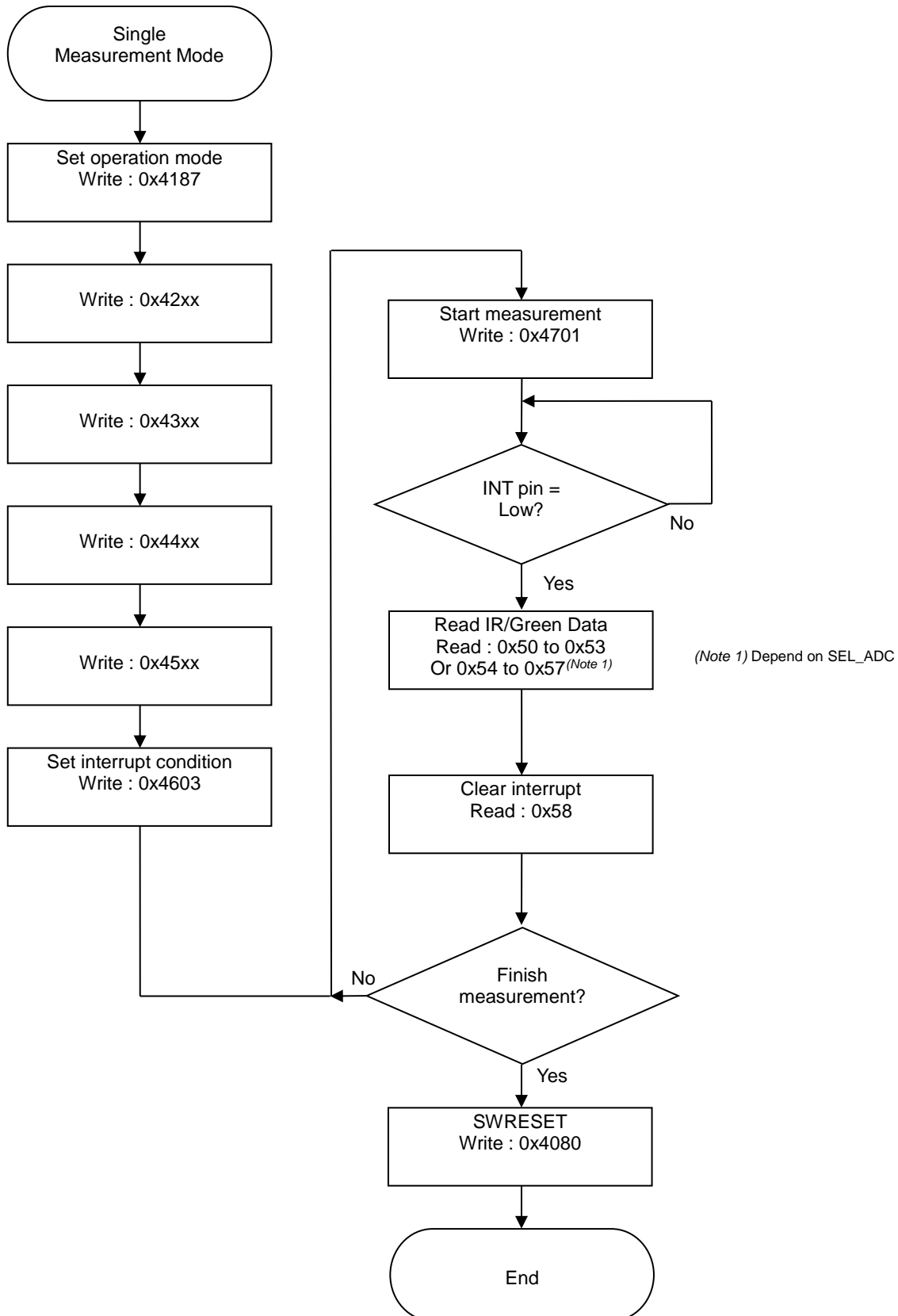
The updated LED current value is reflected after writing 'MEAS_ST = 1'.



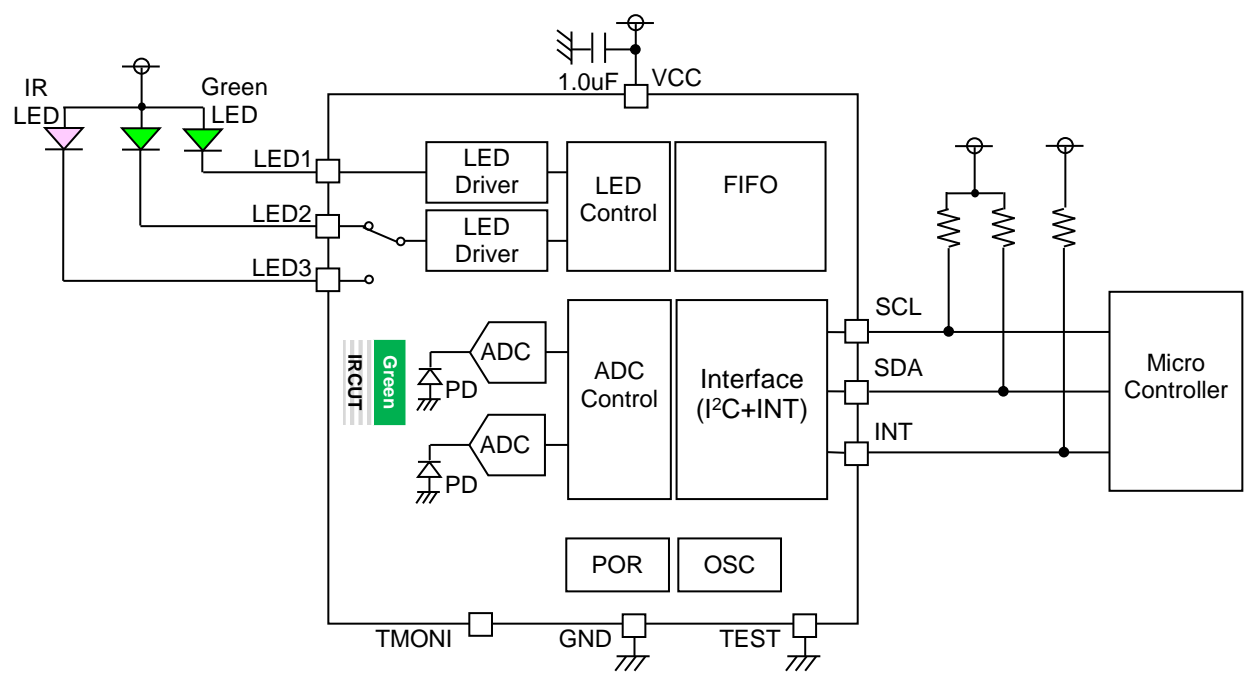
<Non Synchronized Measurement Mode>



<Single Measurement Mode>



Application Example



I/O equivalent circuit

| Equivalent circuit | | Equivalent circuit | |
|-----------------------------|----------------------------|--------------------|----------------------------|
| Pin Name | Equivalent Circuit Diagram | Pin Name | Equivalent Circuit Diagram |
| SCL | | SDA | |
| LED1 LED2 LED3 INT | | TEST | |
| TMONI | | | |

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply terminals.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

8. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

9. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

10. Unused Input Terminals

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

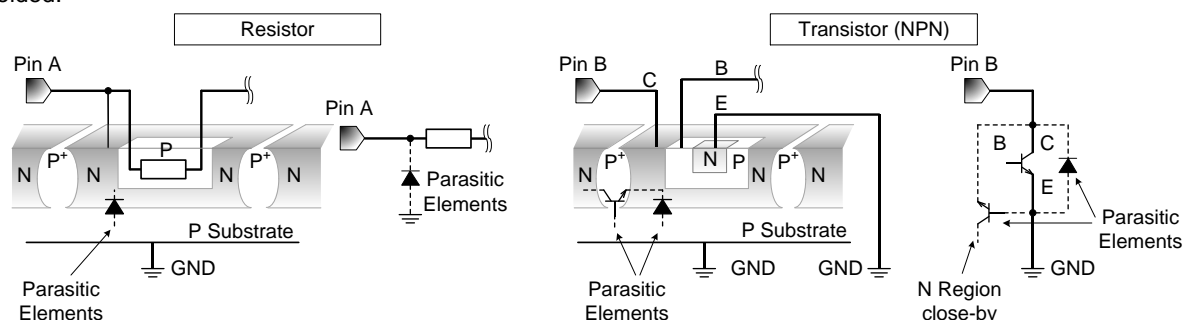
11. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When $GND > Pin A$ and $GND > Pin B$, the P-N junction operates as a parasitic diode.

When $GND > Pin B$, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

**12. Ceramic Capacitor**

When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

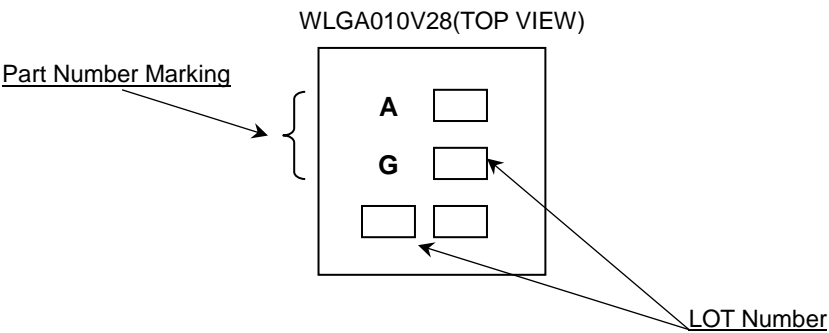
13. Area of Safe Operation (ASO)

Operate the IC such that the output voltage, output current, and the maximum junction temperature rating are all within the Area of Safe Operation (ASO).

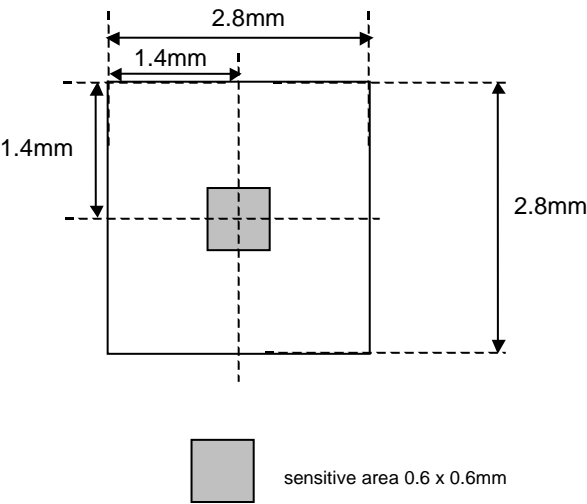
Ordering information

| | | | | | | | | | | | | |
|-------------------|--|--|--|--|--|----------------------------|--|--|--|---|-----|--|
| B H 1 7 9 2 G L C | | | | | | | | | | - | E 2 | |
| Part Number | | | | | | Package GLC: WLGA010V28 | | | | Packaging and forming specification E2: Embossed tape and reel | | |

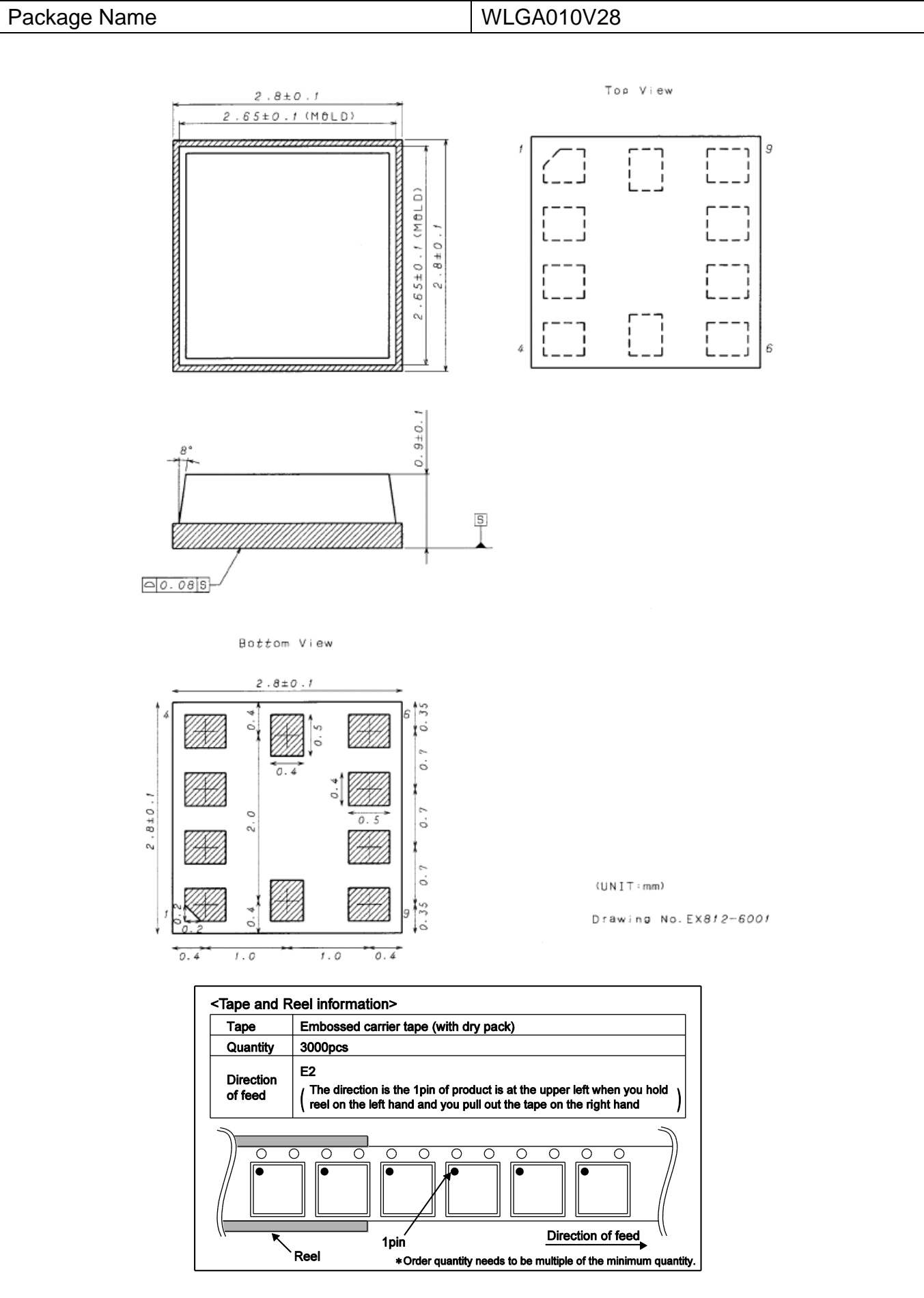
Marking Diagram



Optical design for the device



Physical Dimension and Packing Information



Revision History

| Date | Revision | Changes |
|-------------|----------|---|
| 03.Aug.2017 | 001 | New Release |
| 13.Dec.2017 | 002 | P17 Modify the Synchronized Measurement Mode of Control Sequence. P18 Modify the Timing chart in the Watermark interrupt |

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|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

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 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
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 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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 - [c] the Products are exposed to direct sunshine or condensation
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2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
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| Minimum Package Quantity | 3000 |
| Packing Type | Taping |
| Constitution Materials List | inquiry |
| RoHS | Yes |